

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2816111

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JU-IL LEE	01/16/2004
RECEIVING PARTY DATA	
Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	SAN 136-1, AMI-RI BUBAL-EUB ICHON-SHI
City:	KYOUNGKI-DO
State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF
Postal Code:	467-860
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	7183129
CORRESPONDENCE DATA	
Fax Number:	(312)775-8100
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3127758000
Email:	mhmpto@mcandrews-ip.com
Correspondent Name:	MCANDREWS, HELD & MALLOY, LTD.
Address Line 1:	500 W. MADISON STREET
Address Line 2:	34TH FLOOR
Address Line 4:	CHICAGO, ILLINOIS 60661
ATTORNEY DOCKET NUMBER:	21326US02
NAME OF SUBMITTER:	PETER J. MCANDREWS
SIGNATURE:	/Peter J. McAndrews/
DATE SIGNED:	04/16/2014
Total Attachments: 2	
source=Inventor_Assignment_from_6974715_to_7183129#page1.tif	
source=Inventor_Assignment_from_6974715_to_7183129#page2.tif	

A S S I G N M E N T

Serial No: 10/669996
 Filed: September 24, 2003
 Title: METHOD FOR MANUFACTURING CMOS IMAGE SENSOR USING SPACER ETCHING
BARRIER FILM

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign(s) to Hynix Semiconductor Inc. (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, and in said application and any and all other U.S. applications which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee. The undersigned also hereby authorizes the attorneys of Marshall, Gerstein & Borun to insert the filing date and serial number of this application in the blanks above when they become known.

The undersigned warrant(s) themselves (himself/herself) to be the owners (owner) of the interest herein assigned and to have the right to make this assignment and further warrant(s) that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agree(s), upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application that said assignee, its successors or assigns, may deem necessary or expedient, and for the aforesaid consideration the undersigned further agree(s) upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent in the United States and to vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

SIGNED:

Date: January 16, 2004

LEE Ju-il
Name: LEE, JU-IL

Date: _____

Name: _____

Date: _____

Name: _____

Date: _____

Name: _____